

FIG. 1

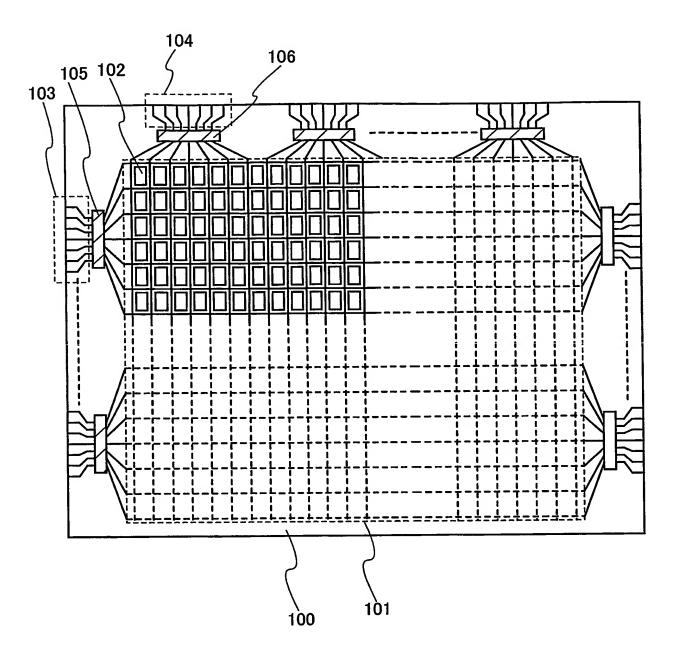


FIG. 2

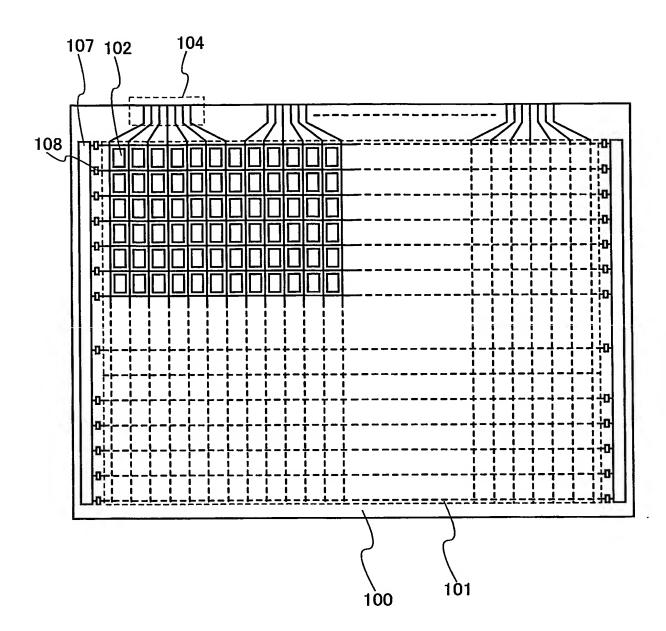
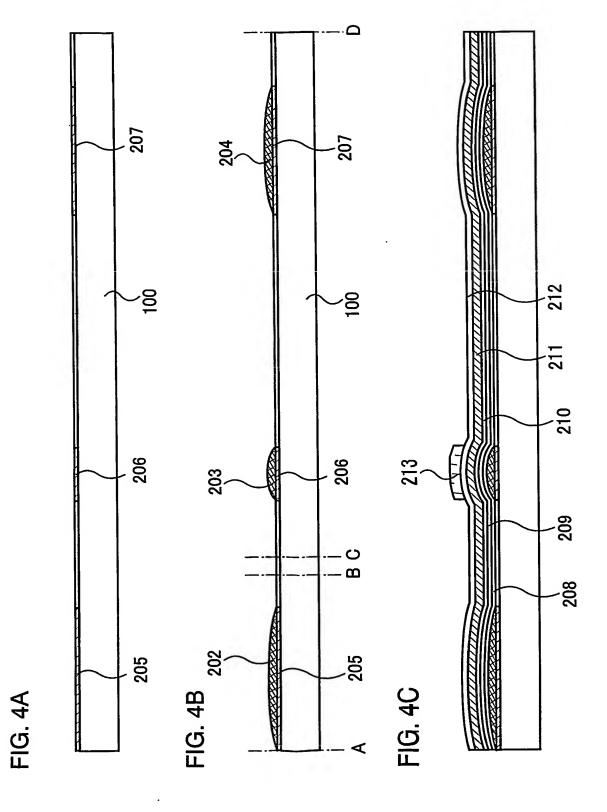
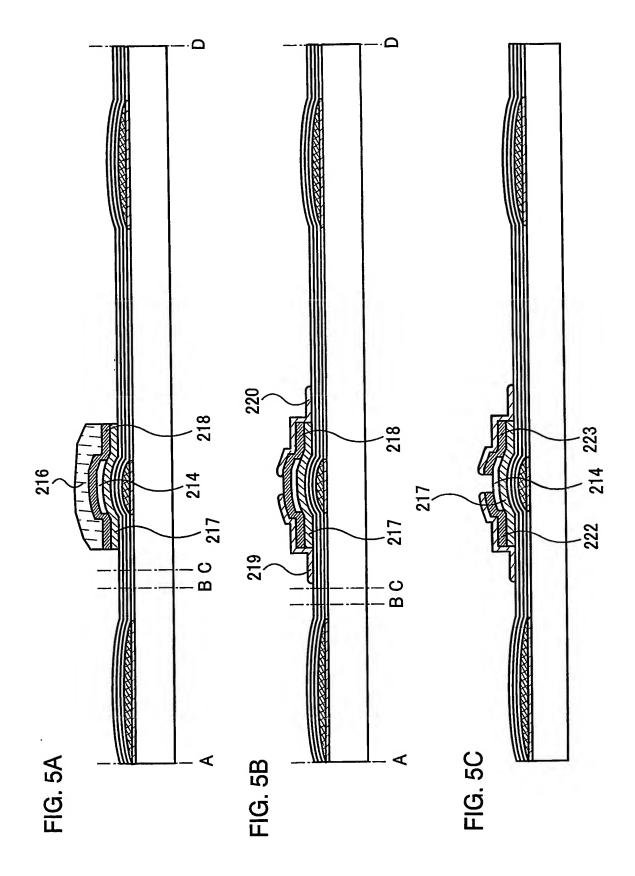
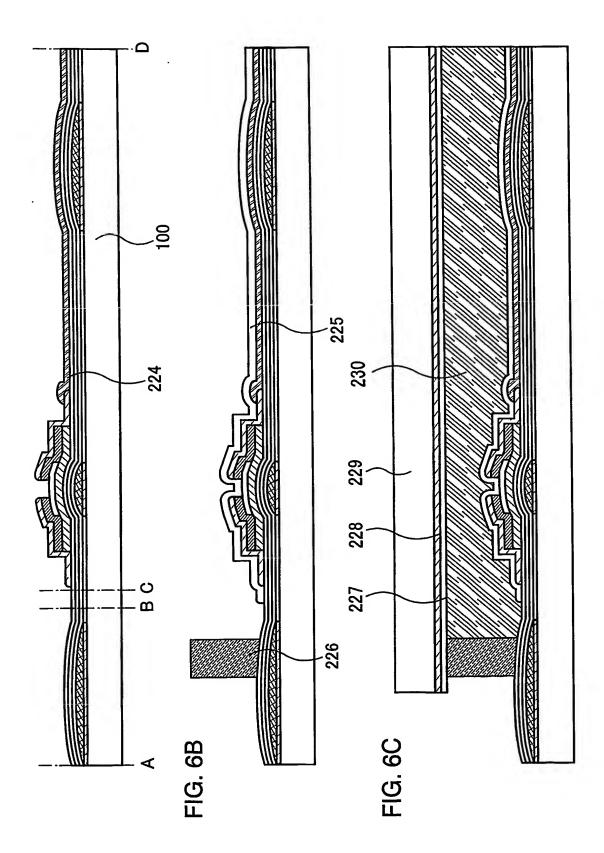


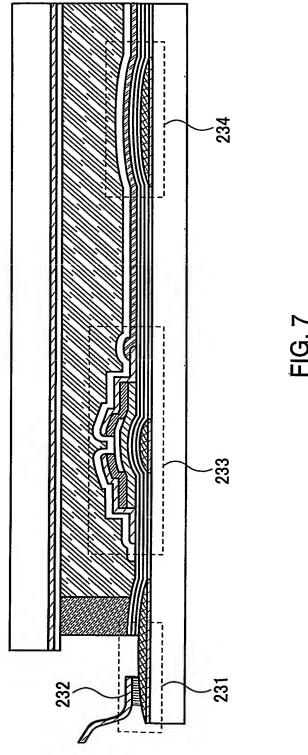
FIG. 3

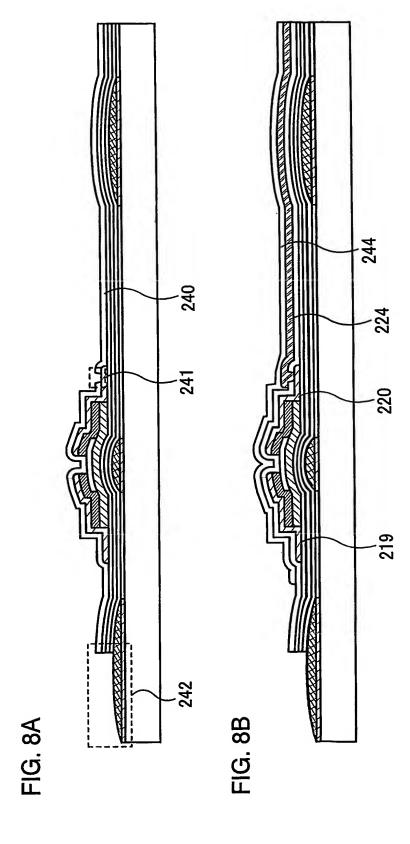


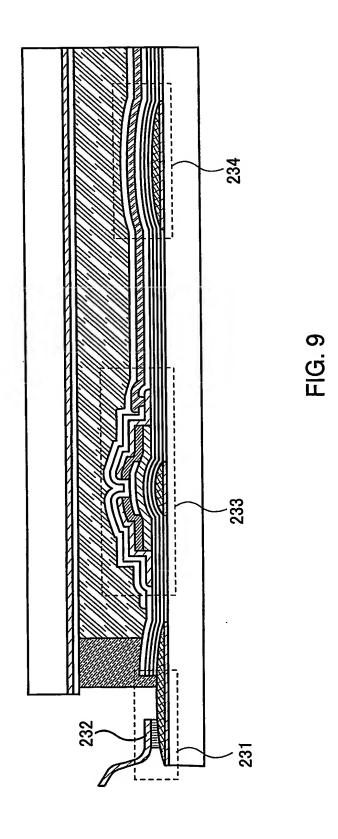


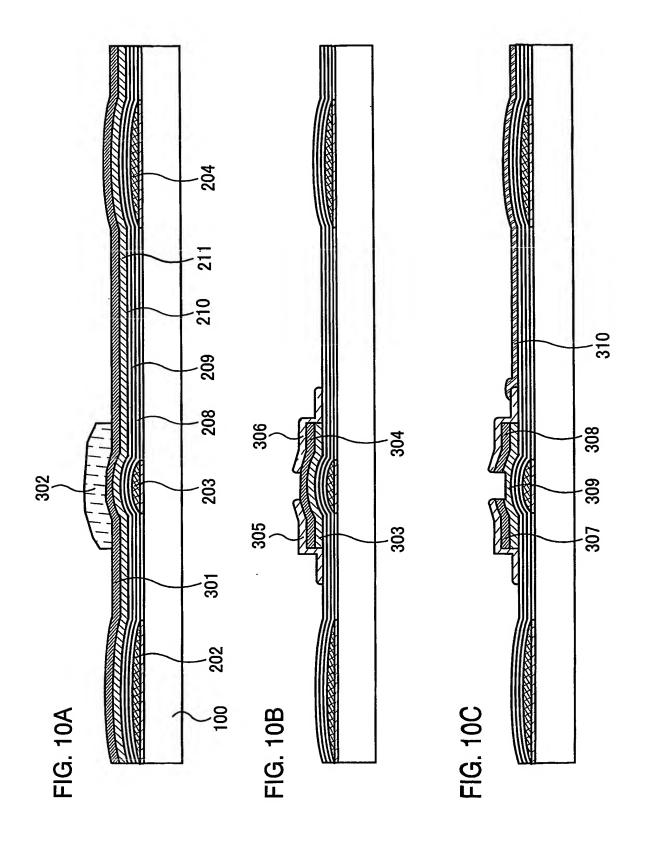


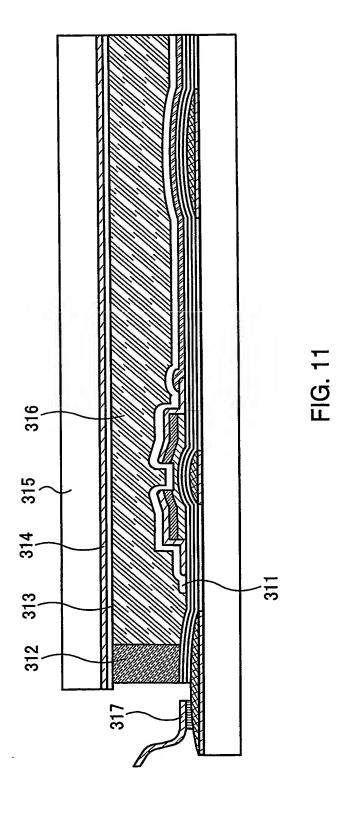
.IG. 6/











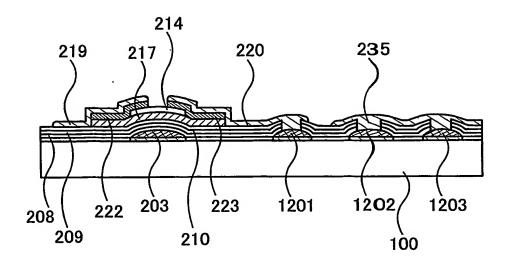


FIG. 12

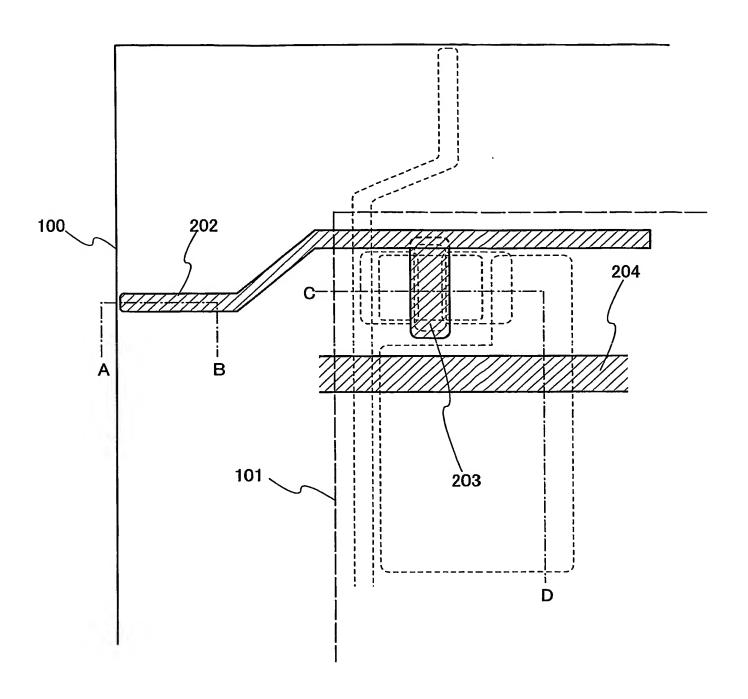


FIG. 13

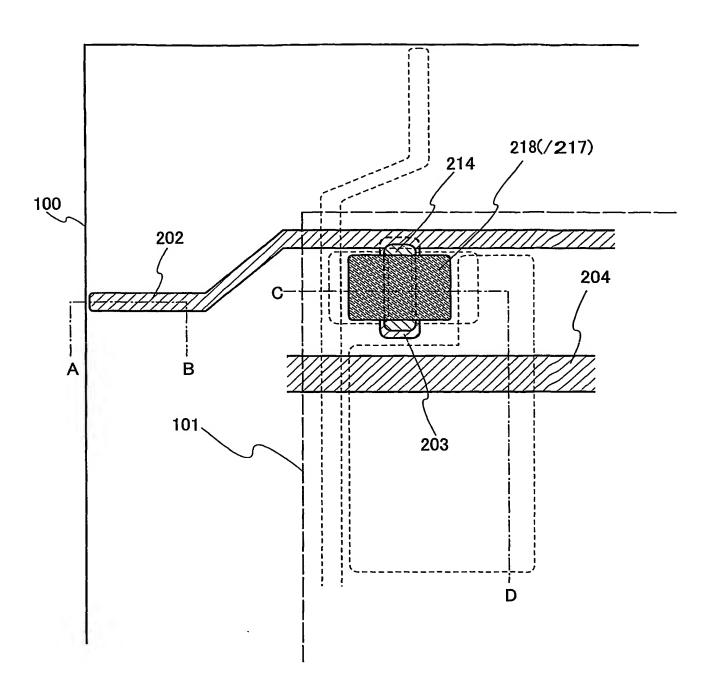


FIG. 14

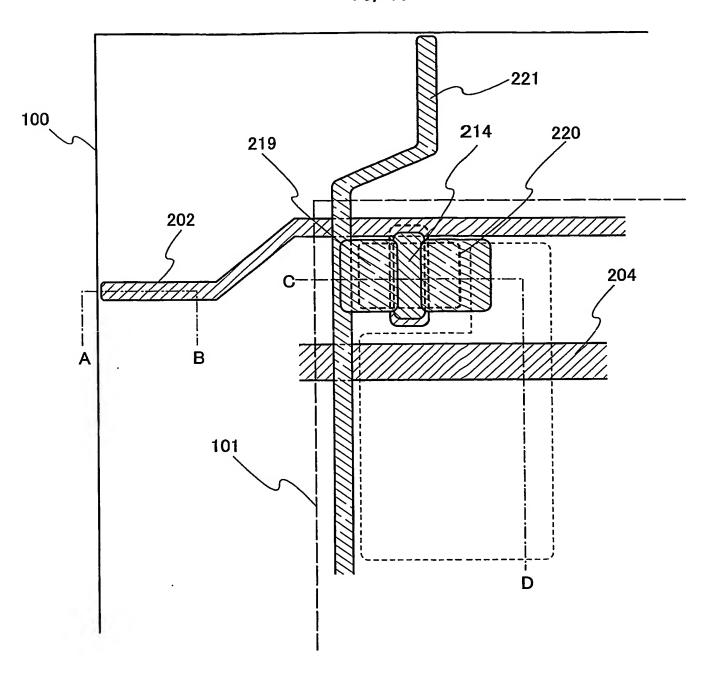


FIG. 15

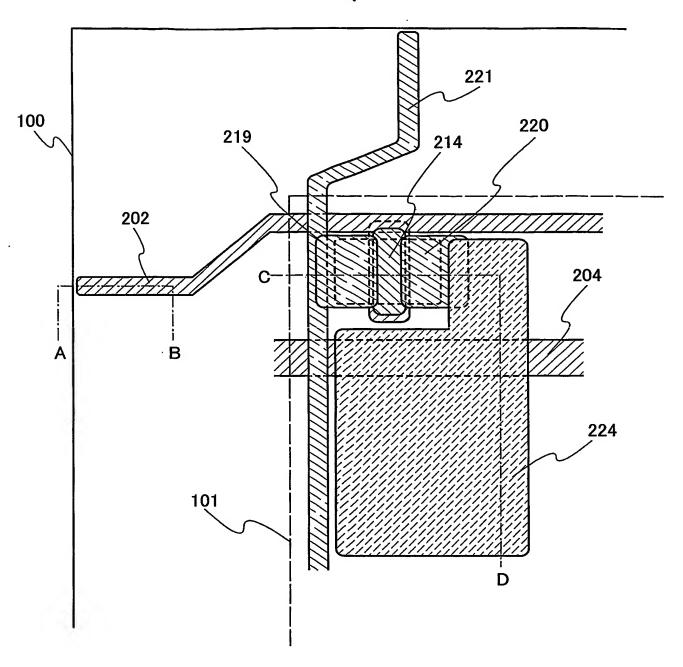


FIG. 16

FIG. 17A

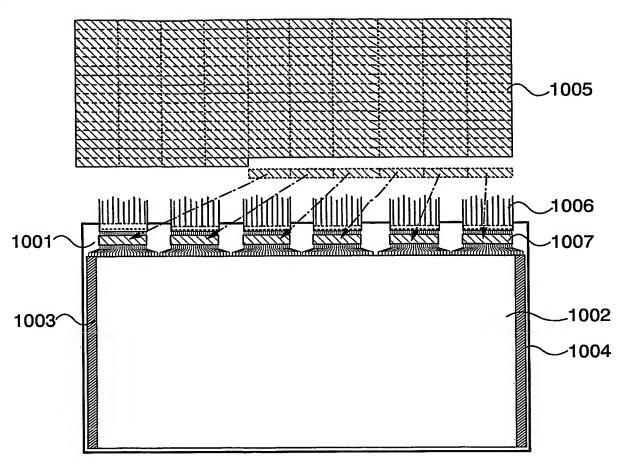


FIG. 17B

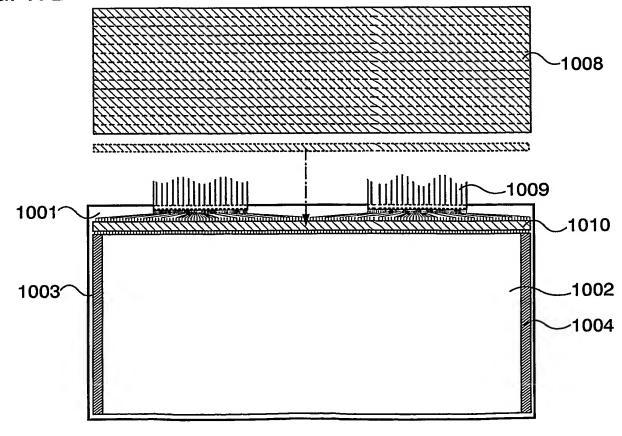


FIG. 19A

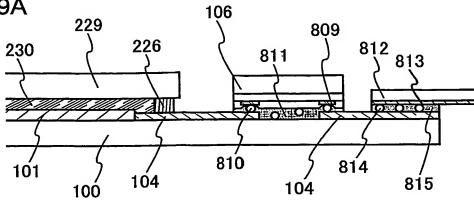


FIG. 19B

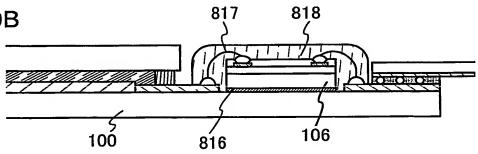


FIG. 18A

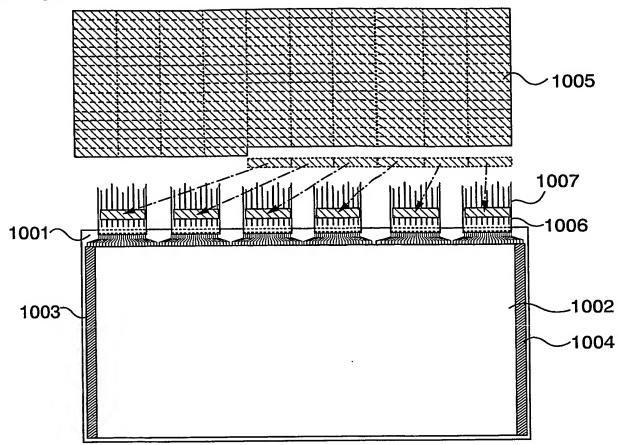
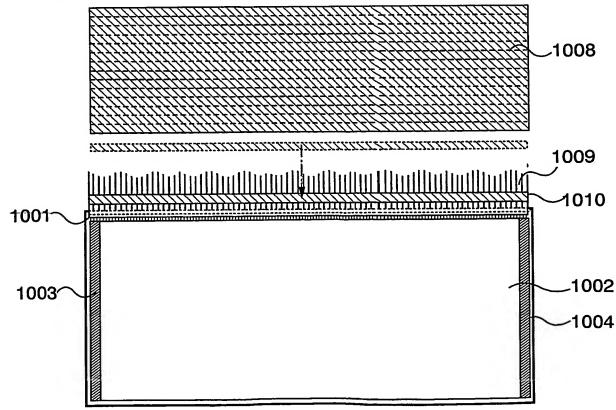


FIG. 18B



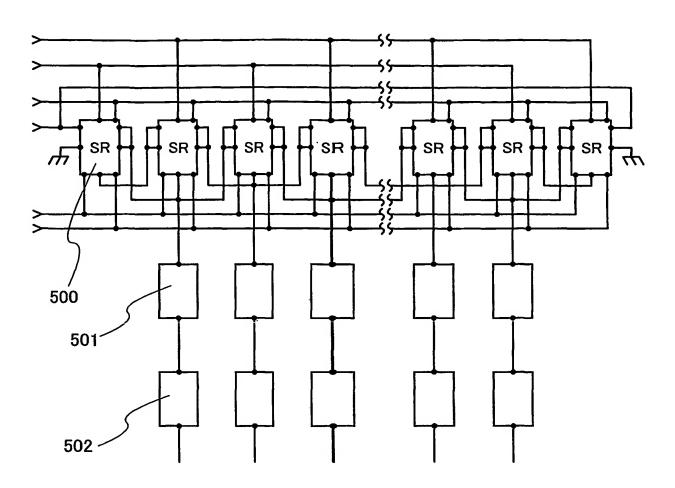


FIG. 20

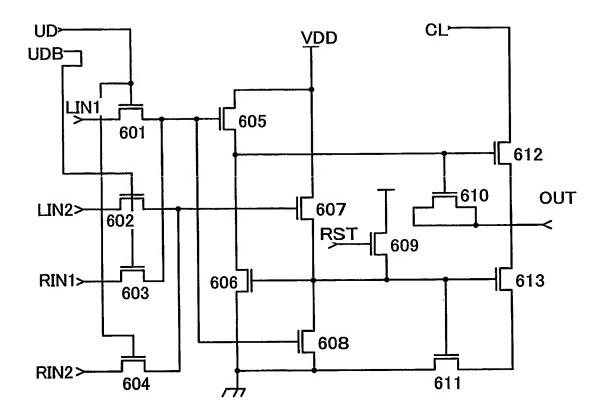


FIG. 21

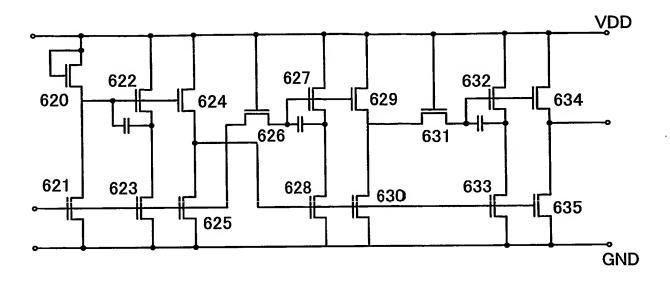


FIG. 22

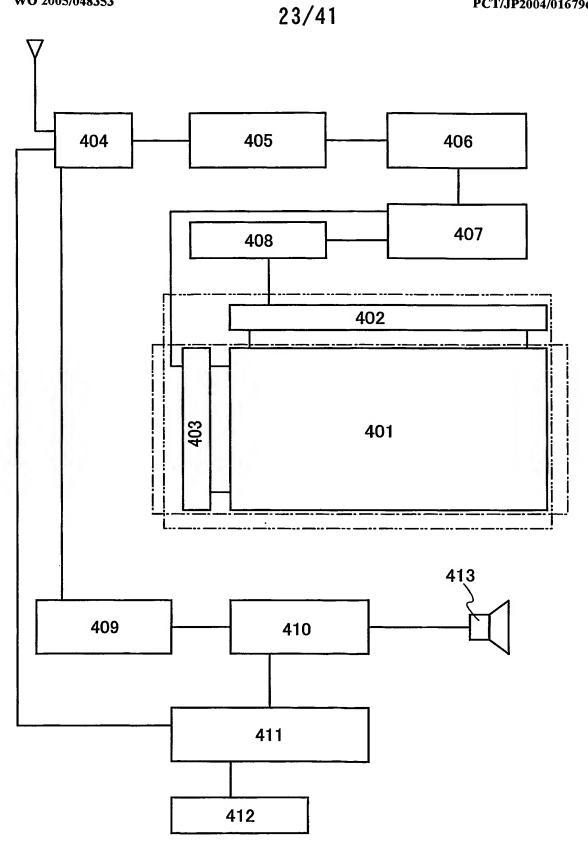


FIG. 23

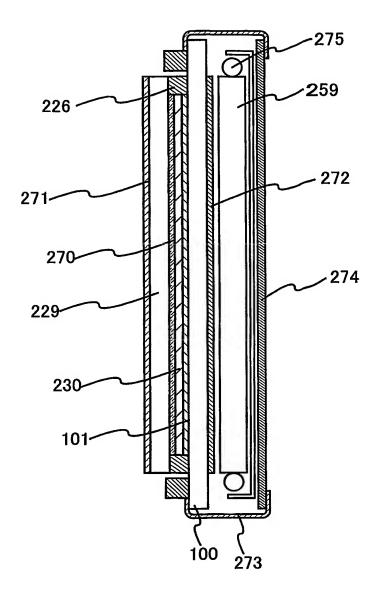


FIG. 24

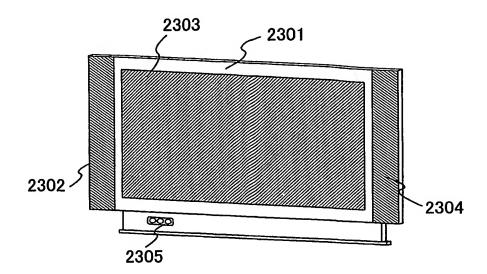
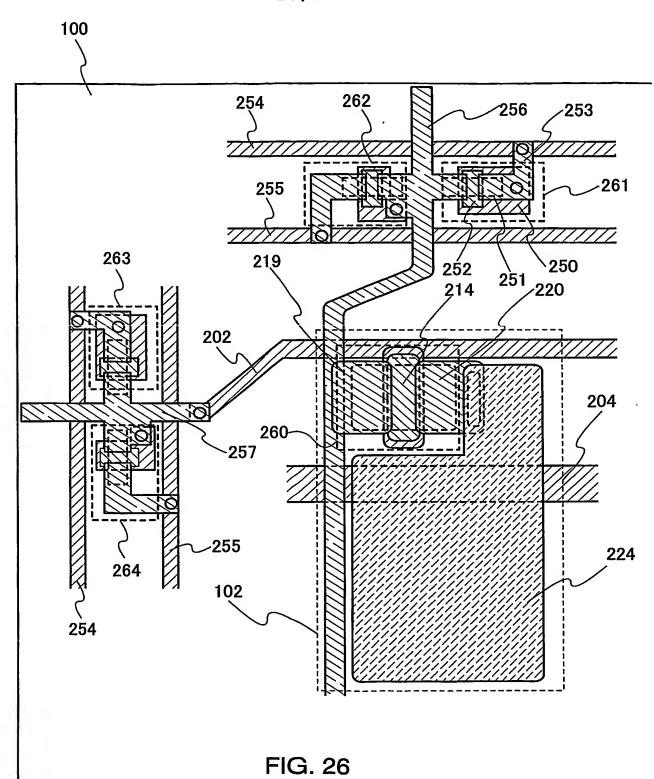


FIG. 25



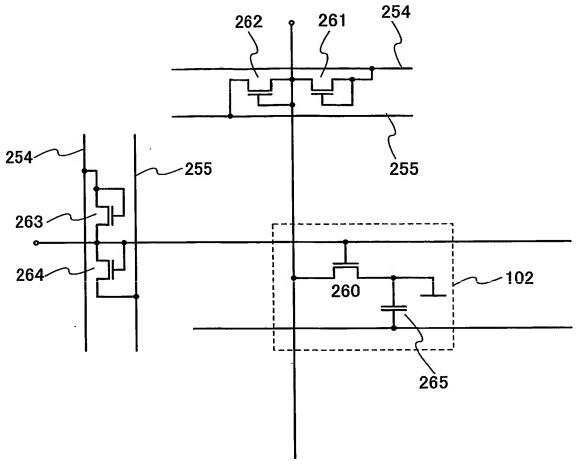


FIG. 27

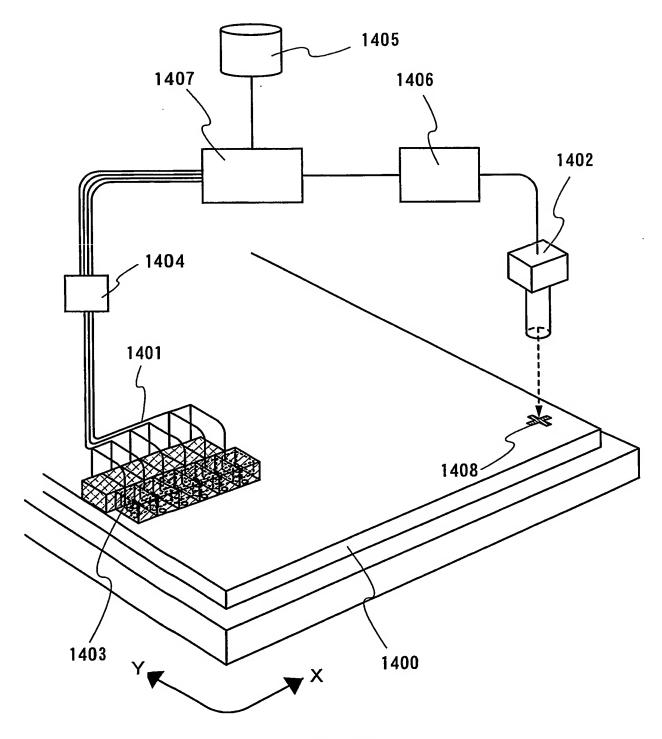
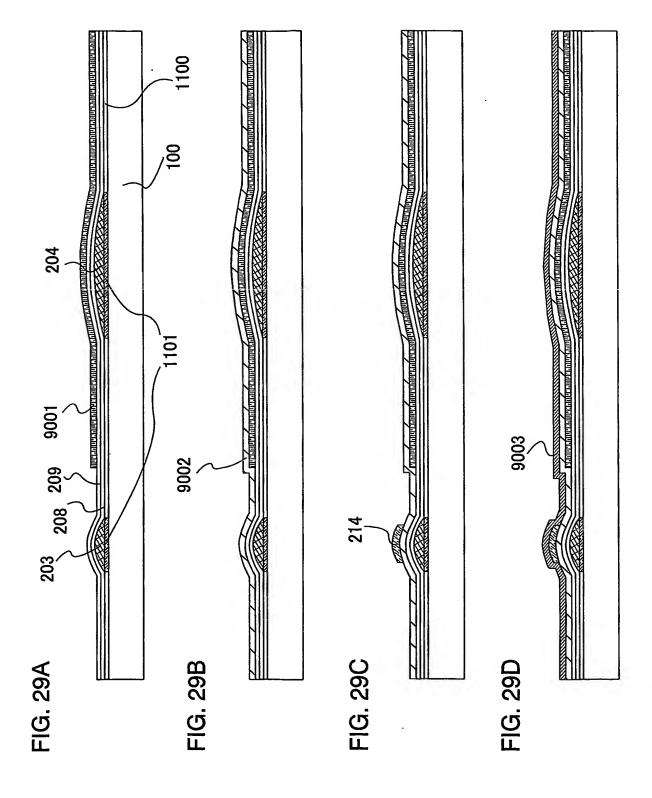
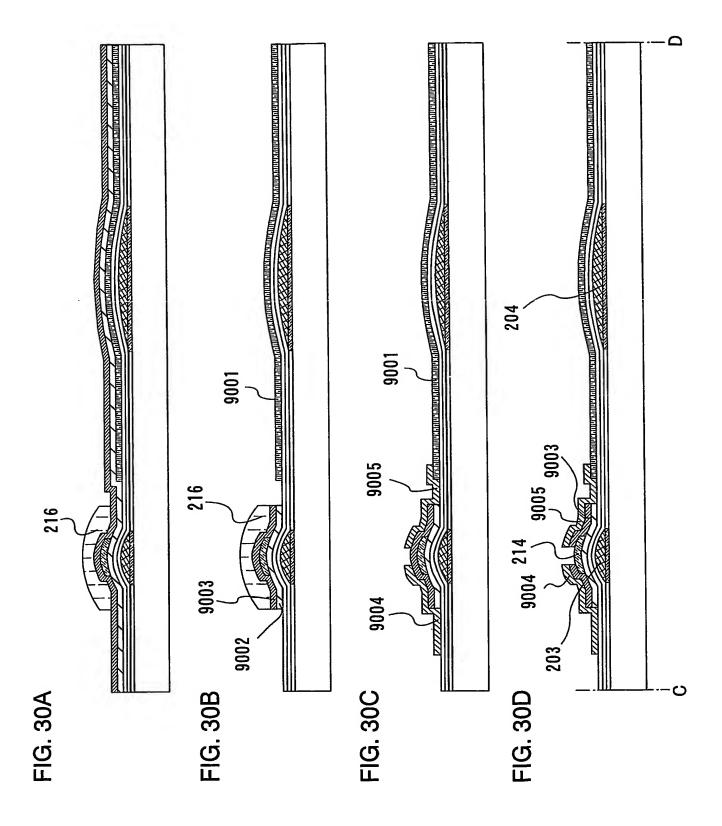
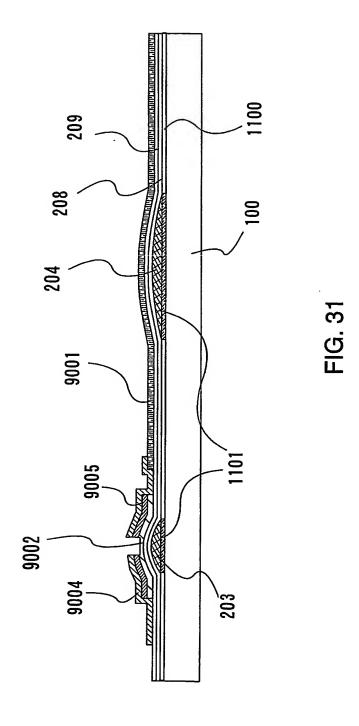
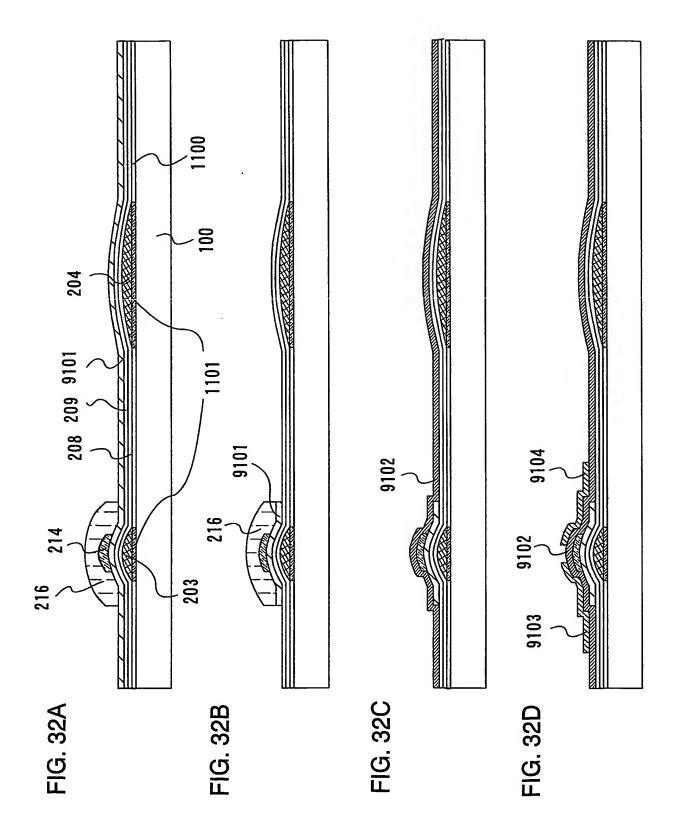


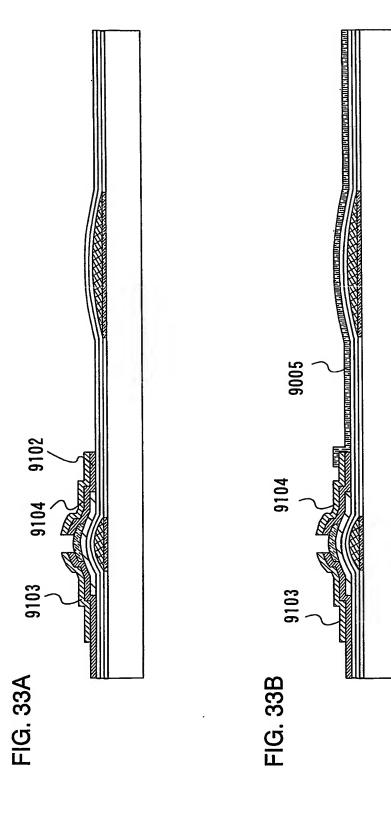
FIG. 28

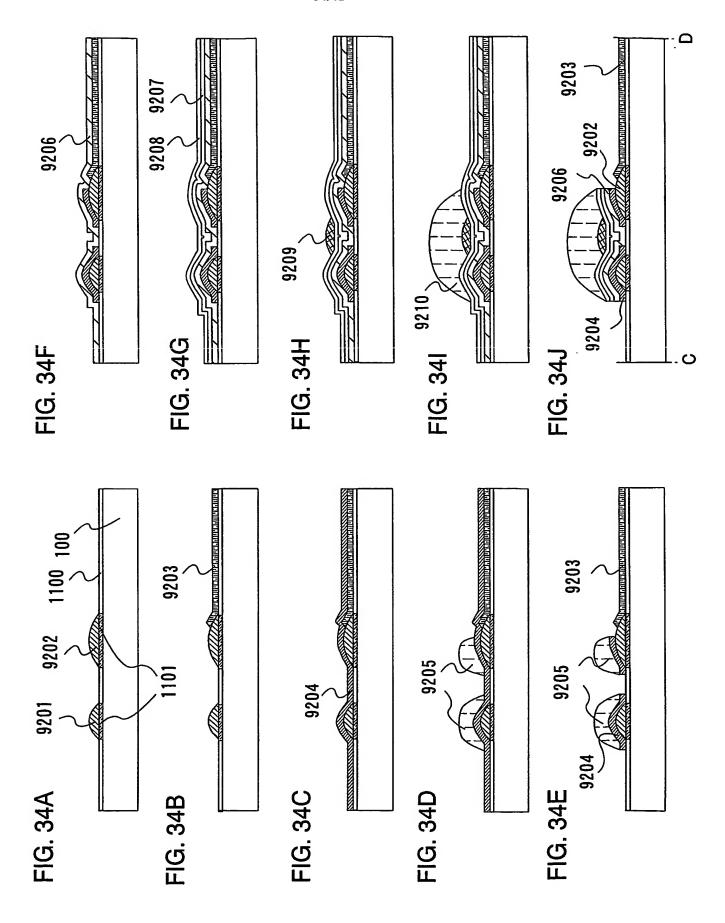


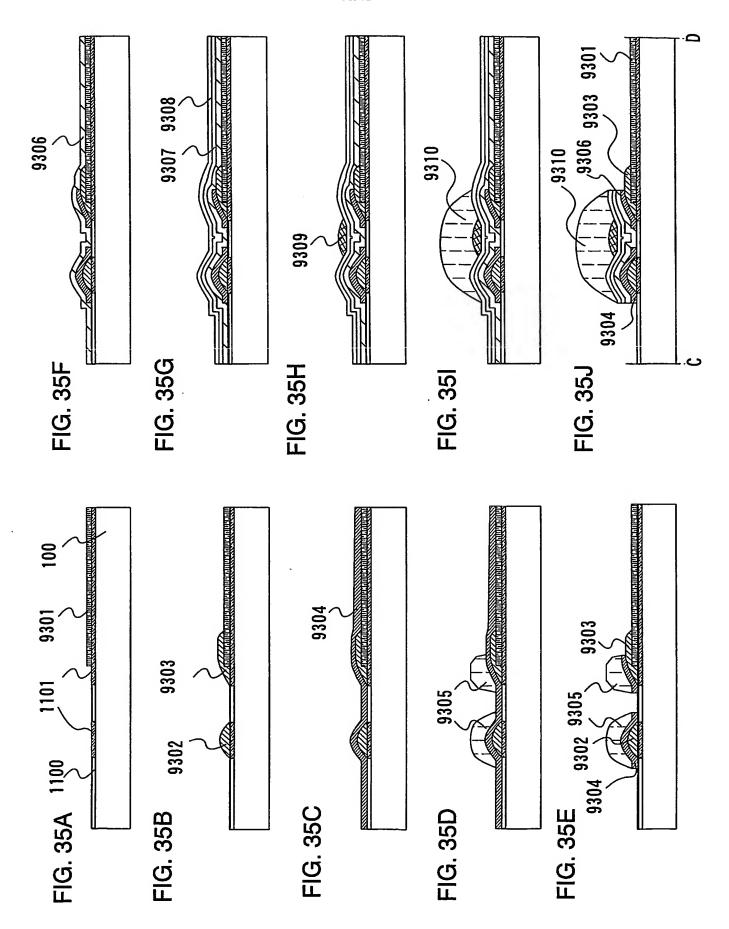






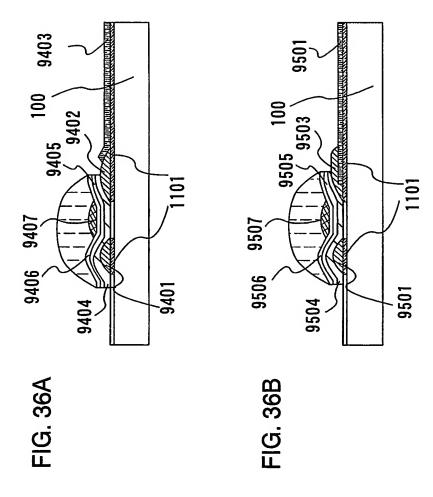






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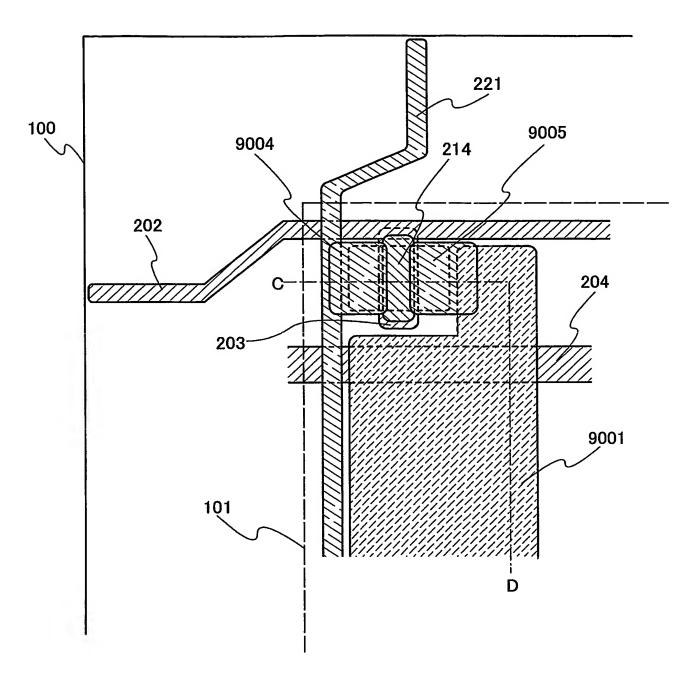


FIG. 37

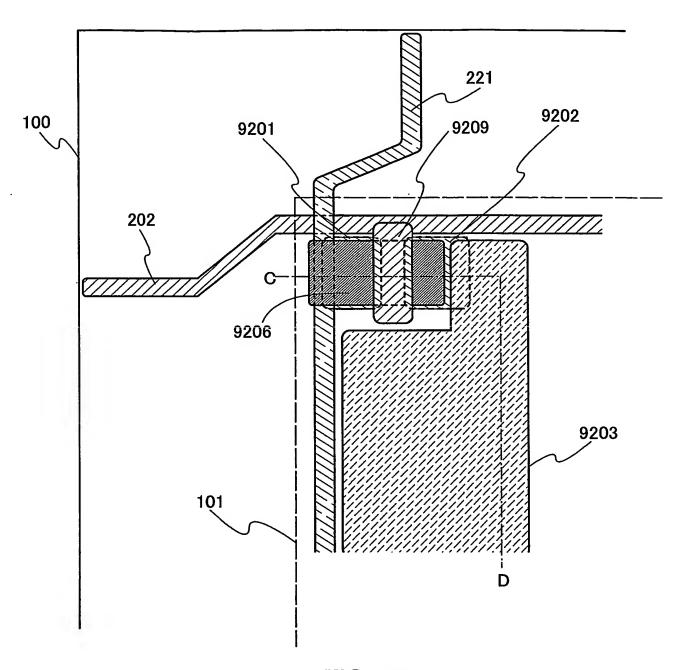


FIG. 38

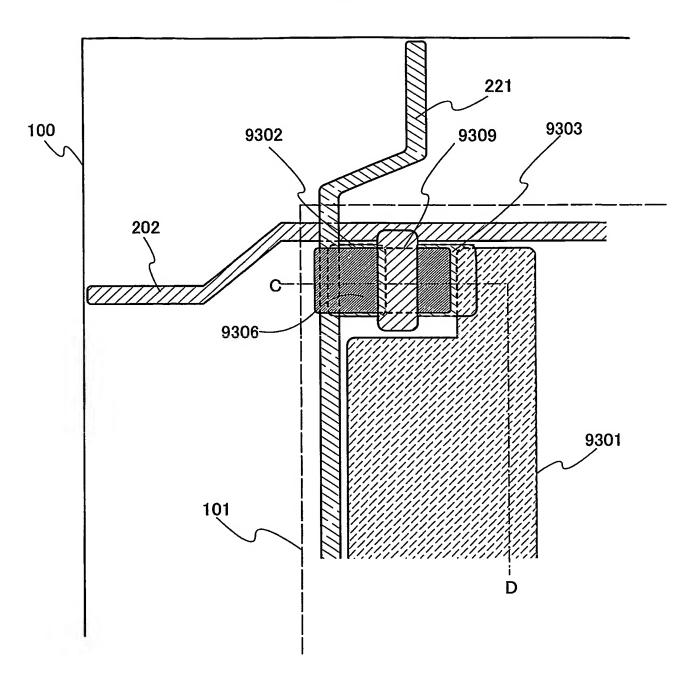


FIG. 39

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## **EXPLANATION OF REFERENCE**

100: substrate, 101: pixel portion, 102: pixel, 103: scanning line side input terminal. 104: signal line side input terminal, 105: driver IC, 106: driver IC, 107: scanning line side driver circuit, 108: protection diode, 201: signal wiring, 202: gate wiring layer, 203: gate electrode layer, 204: capacitor wiring layer, 205: TiO2 layer, 206: TiO2 layer, 207: TiO<sub>2</sub> layer, 208: insulating layer, 209: insulating layer, 210: insulating layer, 211: semiconductor layer, 212: insulating layer, 213: mask, 214: insulating layer, 216: mask, 217: semiconductor layer, 218: semiconductor layer, 219: source-drain wiring layer, 220: source-drain wiring layer, 221: signal wiring, 222: semiconductor layer, 223: semiconductor layer, 224: pixel electrode layer, 225: insulating layer, 226: sealant, 227: insulating layer, 228: conductive layer, 229: opposite substrate, 230: liquid crystal layer, 231: region, 232: wiring board,233: switching TFT, 234: capacitor element, 235: connection wire layer, 240: insulating layer, 241: opening, 242: opening, 244: insulating layer, 250: gate electrode layer, 251: semiconductor layer, 252: insulating layer, 253: wiring layer, 254: common potential line, 255: common potential line, 256: signal wiring layer, 259: light conducting plate, 260: TFT, 261: protection diode, 262: protection diode, 263: protection diode, 264: protection diode, 265: capacitor element. 270: colored layer, 271: polarizing plate, 272: polarizing plate, 273: flexible wiring board, 274: circuit board, 275: cold cathode fluorescent tube, 301: semiconductor layer, 302: mask, 303: semiconductor layer, 304: semiconductor layer, 305: source-drain wiring layer, 306: source-drain wiring layer, 307: semiconductor layer, 308: semiconductor layer, 309: semiconductor layer, 310: pixel electrode layer, 311: insulating layer, 312: sealant, 313: orientation film, 314: opposite electrode, 315: substrate, 316: liquid crystal layer, 317: connection terminal, 401: pixel portion, 402: signal line side driver circuit, 403: scanning line side driver circuit, 404: tuner, 405: video signal amplifier circuit, 406: video signal processing circuit, 407: control circuit, 408: signal dividing circuit, 409: audio signal amplifier circuit, 410: audio signal processing circuit, 411: control circuit, 412: input portion, 413: speaker, 500: pulse output circuit, 501: buffer circuit 502: pixel, 601 to 635:TFT, 811: resin, 812: FPC, 813: wiring, 814: conductive particle, 815: resin, 816: adhesive, 817: wiring, 818: sealing resin, 1001: substrate, 1002: pixel portion, 1003: driver circuit, 1004: driver circuit, 1005: substrate, 1006: tape, 1007: IC chip, 1008: substrate, 1009: tape, 1010: IC chip, 1100: Ti film, 1101: activation region, 1201: connection wiring layer, 1202: connection wiring layer, 1203: connection wiring layer, 1400: substrate, 1401: droplet discharge means, 1402: imaging means, 1403: head, 1404: control means, 1405: storage medium,

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1406: image processing means, 1407: computer, 1408: marker, 2301: module chassis, 2302: speaker, 2303: display screen, 2304: speaker, 2305: operation switch, 9001: pixel electrode, 9002: semiconductor layer, 9003: semiconductor layer, 9004: source-drain wiring layer, 9005: source-drain wiring layer, 9101: semiconductor layer, 9102: semiconductor layer, 9103: source-drain wiring, 9104: source-drain wiring, 9105: pixel electrode, 9201: source-drain wiring layer, 9202: source-drain wiring layer, 9203: pixel electrode, 9204: semiconductor layer, 9205: mask, 9206: semiconductor layer, 9207: gate insulating film, 9208: gate insulating film, 9209: pixel electrode, 9210: mask, 9301: pixel electrode, 9302: source-drain wiring layer, 9303: source-drain wiring layer, 9304: semiconductor layer, 9305: mask, 9306: semiconductor layer, 9307: gate insulating film, 9308: gate insulating film, 9309: gate electrode, 9310: mask